



## Material Content Data Sheet



Sales Product Name	BTS50070-1TMA			Issued		29. August 2013		
MA#	MA001044084							
Package	PG-TO220-7-4			Weight*		1525.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.391	0.42	0.42	4188	4188
leadframe	non noble metal	iron	7439-89-6	0.910	0.06		597	
	inorganic material	phosphorus	7723-14-0	0.273	0.02		179	
	non noble metal	copper	7440-50-8	909.052	59.57	59.65	595805	596582
wire	non noble metal	aluminium	7429-90-5	2.384	0.16	0.16	1562	1562
encapsulation	organic material	carbon black	1333-86-4	8.856	0.58		5804	
	plastics	epoxy resin	-	97.412	6.38		63845	
	inorganic material	silicondioxide	60676-86-0	484.107	31.73	38.69	317291	386940
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7924	7924
plating	non noble metal	nickel	7440-02-0	0.216	0.01		141	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	141
glue	plastics	Polyimide	26023-21-2	0.143	0.01	0.01	93	93
solder	noble metal	silver	7440-22-4	0.098	0.01		64	
	non noble metal	tin	7440-31-5	0.078	0.01		51	
	non noble metal	lead	7439-92-1	3.746	0.25	0.27	2455	2570
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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